



SOT1333-1

DFN2520-9: plastic extremely thin small outline package; no leads; 9 terminals; body 2 x 2.5 x 0.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN2520-9
Package type industry code	XSON9
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-252
Mounting method type	S (surface mount)
Issue date	1-5-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.4	-	2.5	2.6	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	9	-	



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2. Package outline

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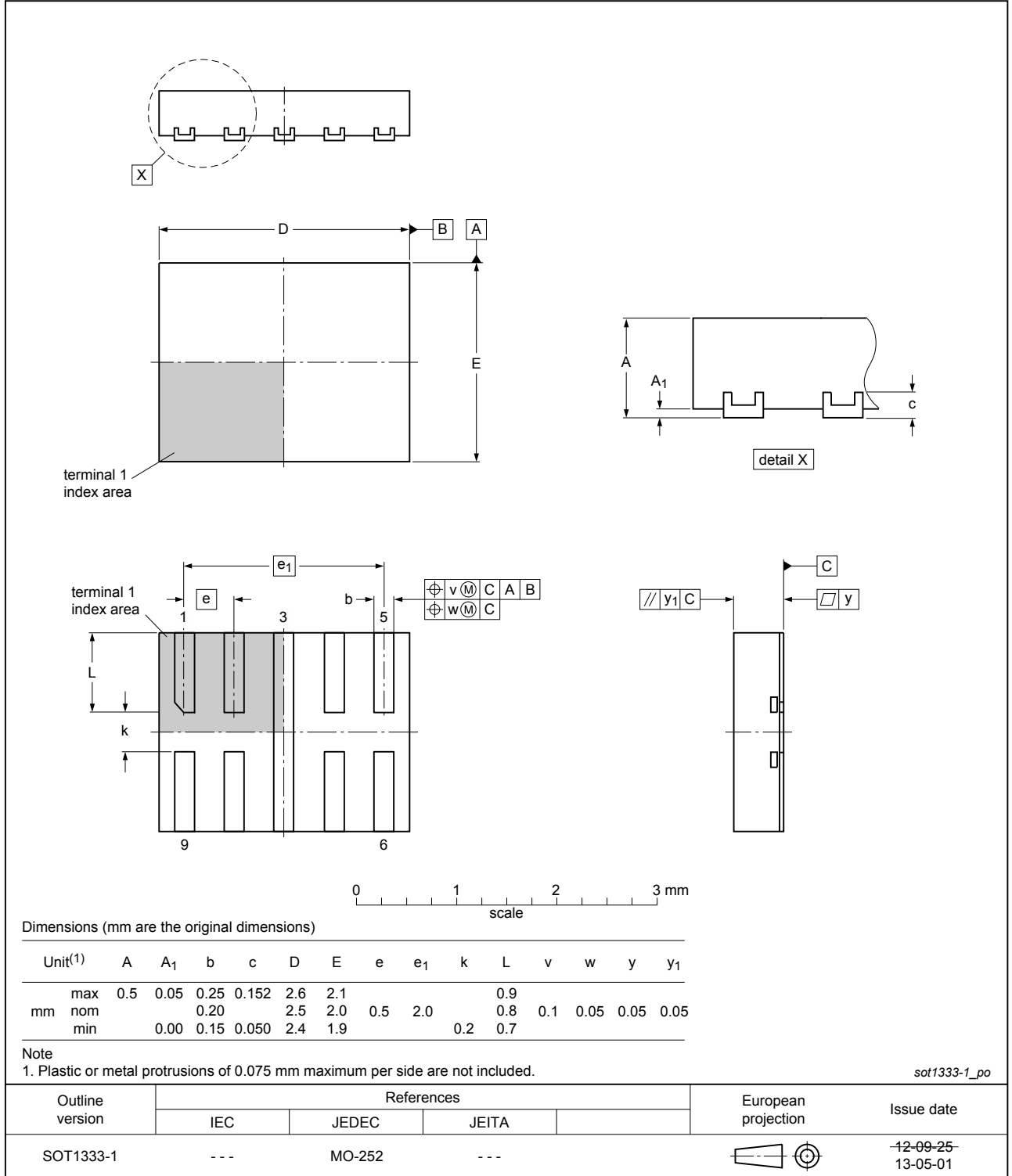


Fig. 1. Package outline XSON9 (SOT1333-1)

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3. Soldering

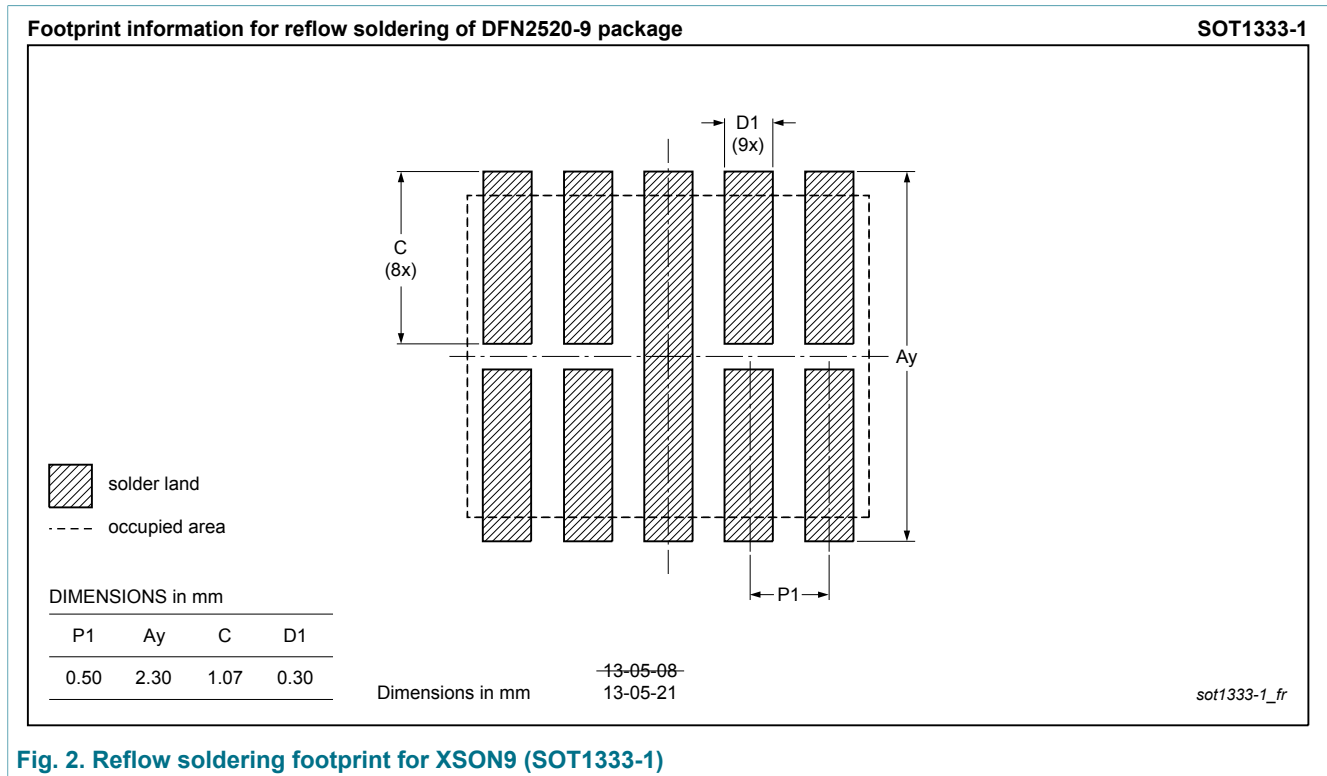


Fig. 2. Reflow soldering footprint for XSON9 (SOT1333-1)

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4. Legal information

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